

**What is claimed is:**

1           1.    A bond pad for a flip chip package, suitable  
2           for an integrated circuit chip, comprising:

3                at least one slot extending along a direction which  
4                is perpendicular to a radial direction from the  
5                center of the integrated circuit chip.

1           2.    The bond pad as claimed in claim 1, wherein the  
2           bond pad is located substantially at corners of the  
3           integrated circuit chip.

1           3.    The bond pad as claimed in claim 1, wherein the  
2           patterns are arranged substantially in an array.

1           4.    The bond pad as claimed in claim 1, wherein the  
2           bond pad is circular or rectangular.

1           5.    The bond pad as claimed in claim 1, wherein the  
2           slot is rectangular.

1           6.    The bond pad as claimed in claim 1, wherein the  
2           slot extends at least partially through the bond pad.

1           7.    The bond pad as claimed in claim 1, wherein the  
2           slot extends down to the bottom of the bond pad.

1           8.    A bond pad for a flip chip package, suitable  
2           for an integrated circuit chip, comprising:

3                a plurality of parallel slots located in the bond  
4                pad, each of the slots extending along a  
5                direction which is perpendicular to a radial  
6                direction from the center of the integrated

7 circuit chip, wherein the bond pad deposited at  
8 the corner of the integrated circuit chip.

1 9. The bond pad as claimed in claim 8, wherein the  
2 bond pad is circular or rectangular.

1 10. The bond pad as claimed in claim 8, wherein the  
2 slot is rectangular.

1 11. The bond pad as claimed in claim 8, wherein the  
2 slot extends at least partially through the bond pad.

1 12. The bond pad as claimed in claim 8, wherein the  
2 slot extends down to the bottom of the bond pad.

1 13. A bond pad structure for a flip chip package,  
2 suitable for an integrated circuit chip, the integrated  
3 circuit chip having a rectangular shape, comprising:

4 a plurality of bond pads located in each of the  
5 quadrants of the integrated circuit chip,  
6 wherein each of the bond pads comprises at  
7 least one slot and each of the slots in the  
8 same quadrant extending along a direction which  
9 is substantially perpendicular to the diagonal  
10 lines of the integrated circuit chip passing  
11 through the quadrant in which it is located.

1 14. The bond pad as claimed in claim 13, wherein  
2 the patterns are arranged substantially in an array.

1 15. The bond pad as claimed in claim 13, wherein  
2 the slot is rectangular.

1           16. The bond pad as claimed in claim 13, wherein  
2 the slot extends at least partially through the bond pad.

1           17. The bond pad as claimed in claim 13, wherein  
2 the slot extends down to the bottom of the bond pad.

1           18. The bond pad as claimed in claim 13, wherein  
2 the bond pad is circular or rectangular.

1           19. A semiconductor device, comprising:

2 a substrate;

3 a conductive layer, disposed on the substrate; and

4 at least one bond pad, disposed on the conductive  
5 layer, wherein the bond pad comprises at least  
6 one slot extending along a direction which is  
7 perpendicular to a radial direction from the  
8 center of the surface of the substrate.

1           20. The bond pad as claimed in claim 19, wherein  
2 the number of the bond pad located in the quadrants of  
3 the integrated circuit chip is more than one, and each of  
4 the slots in the same quadrant extending along a  
5 direction which is substantially perpendicular to the  
6 diagonal lines of the integrated circuit chip passing  
7 through the quadrant in which it is located.

1           21. The bond pad as claimed in claim 19, wherein  
2 the slot is rectangular.

1           22. The bond pad as claimed in claim 19, wherein  
2 the slot extends at least partially through the bond pad.

1           23. The bond pad as claimed in claim 19, wherein  
2 the slot extends down to the bottom of the bond pad.